

Filename: PMP8970_REVA_bom.xls

Date: 06/12/2013

PMP8970_REVA BOM

COUNT	RefDes	Value	Description	Size	Part Number	Mfr
1	C1	220uF	Capacitor, Aluminum, 400V	30 x 30mm	ECOS2GP221DA	Panasonic
1	C12	100uF	Capacitor, Aluminum Electrolytic, 25V	0.248 inch	25V ZL 100uF 6.3 X 11	Rubycon
1	C13	1500pF	CAP, CERM DISC Y1, 250Vac, 20%	.500 X .310	ECKDNA152ME	Panasonic
1	C14	0.047uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H473K	TDK
2	C15, C18	100pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H101K	TDK
1	C16	0.01uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H103K	TDK
1	C17	0.1uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	C1608X7R1H104K	TDK
2	C2, C3	0.22 uF	Capacitor, Film, 250VAC, 20%	0.689 x 0.217	STD	STD
1	C4	0.01uF	Capacitor, Polyester Film, 250V, 10%	0.311 x 0.213 inch	ECQ-E2103KB	Panasonic
1	C5	DNP	Do Not Populate	0603	N/A	N/A
2	C6, C11	1uF	Capacitor, Ceramic, 16V, X7R, 20%	0603	C1608X7R1C105M	TDK
4	C7, C8, C9, C10	2700uF	Capacitor, Aluminum Electrolytic, 25V, 3.45A rms ripple	0.571 inch	25V ZL 2700uF 16 X 25	Rubycon
1	D1	KBP06G	Diode, Bridge Rectifier, 1.5A, 600V	0.580 x 0.145 inch	KBP06G	Diodes
1	D2	MBRF30H100CT	Diode, Dual Schottky, 30A, 100V	TO-220	MBRF30H100CT	ON Semi
1	D3	MURA160T3	Diode, Rectifier, 1A, 600V	SMA	MURA160T3	ON Semiconductor
1	D4	MMSD914	Diode, Switching, 100-V, 200-mA, 225-mW	SOD-123	MMSD914T1	On Semi
1	F1	2.5A/250V	Fuse, TR5 Series, 2.5A, 250V	0.335	3701250041	Wickmann
1	HS1	HS350	Heatsink, Vertical-mount, Multipackages	25.4 x 42.0 mm	529802B02500G	Thermalloy
1	HS2	513201	HEATSINK TO-220 W/PINS 1inch TALL	0.5x1.38in.	531002B02500G	Aavid
1	J1		Terminal Block, 2-pin, 6-A, 3.5mm	0.27 x 0.25"	ED1514	OST
1	L1	450uH	Inductor, Power Choke, 1.5A	C CODE	I01-0450-01-00	ICE
1	L2	10 uH	Inductor, Common Mode Cok	12.70 x 18.16 mm	ICA 1069	ICE Components
1	L3	9.5 mH	Inductor, Line Filter	18.5 x 25.5 mm	LF24012-0095-V	ICE Components
1	L4	2.2uH	Inductor, Power,	0.350 x 0.300 inch	RFB0807-2R2L	Coilcraft
1	Q1	SPP11N60C3	Trans, Cool MOS Power Nchan, 650V, 11A, 380 milliohm	TO-220AB	SPP11N60C3	Infineon
4	R1, R2, R3, R4	30.1k	Resistor, Chip, 1-W, 5%	2512	Std	Std
1	R11	10	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R12, R15	0	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R13, R21	DNP	Do Not Populate	0603	N/A	N/A
1	R14	150k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R16	698	Resistor, Chip, 1/16W, 1%	0603	Std	Std
2	R17, R20	4.99k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R18	100k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R19	27.4k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R22	1.21k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
1	R23	21.5k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
5	R24, R25, R26, R27, R28	1	Resistor, Chip, 1/16W, x%	0805	Std	Std
1	R5	DNP	Do Not Populate	1206	N/A	N/A
3	R6, R7, R9	332k	Resistor, Chip, 1/16W, x%	0805	Std	Std
2	R8, R10	499k	Resistor, 1/4 watt, 5%	1206	Std	Std
1	RT1	S10K320	MOV, 50W	0.472 x 0.157 inch	B72210S03321K101	Epcos

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1	T1	240 uH	XFMR, Flyback, Custom	34.5 x 36.00 mm	TT10050-3	
3	TP1, TP2, TP3	5000	Test Point, Red, Thru Hole Color Keyed	0.100 x 0.100 inch	5000	Keystone
1	TP4	5001	Test Point, Black, Thru Hole Color Keyed	0.100 x 0.100 inch	5001	Keystone
1	TP6	5002	Test Point, White, Thru Hole Color Keyed	0.100 x 0.100 inch	5002	Keystone
1	U1	UCC28600D	IC, Quasi-Resonant Flyback Green Mode Controller	SO8	UCC28600D	Texas Instruments
1	U2	H11A817A	IC, Optocoupler, 5300-V, 80-160% CTR	0.380 x 0.180 inch	H11A817A	Fairchild
1	U3	TL431AILP	IC, Adj Shunt Regulator	T0-92	TL431AILP	TI

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